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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	H8/300H
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, SCI, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	29
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 8x10b SAR
Oscillator Type	External, Internal
Operating Temperature	-20°C ~ 75°C (TA)
Mounting Type	Surface Mount
Package / Case	64-BQFP
Supplier Device Package	64-QFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/hd64f3694hv

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1.2 Internal Block Diagram

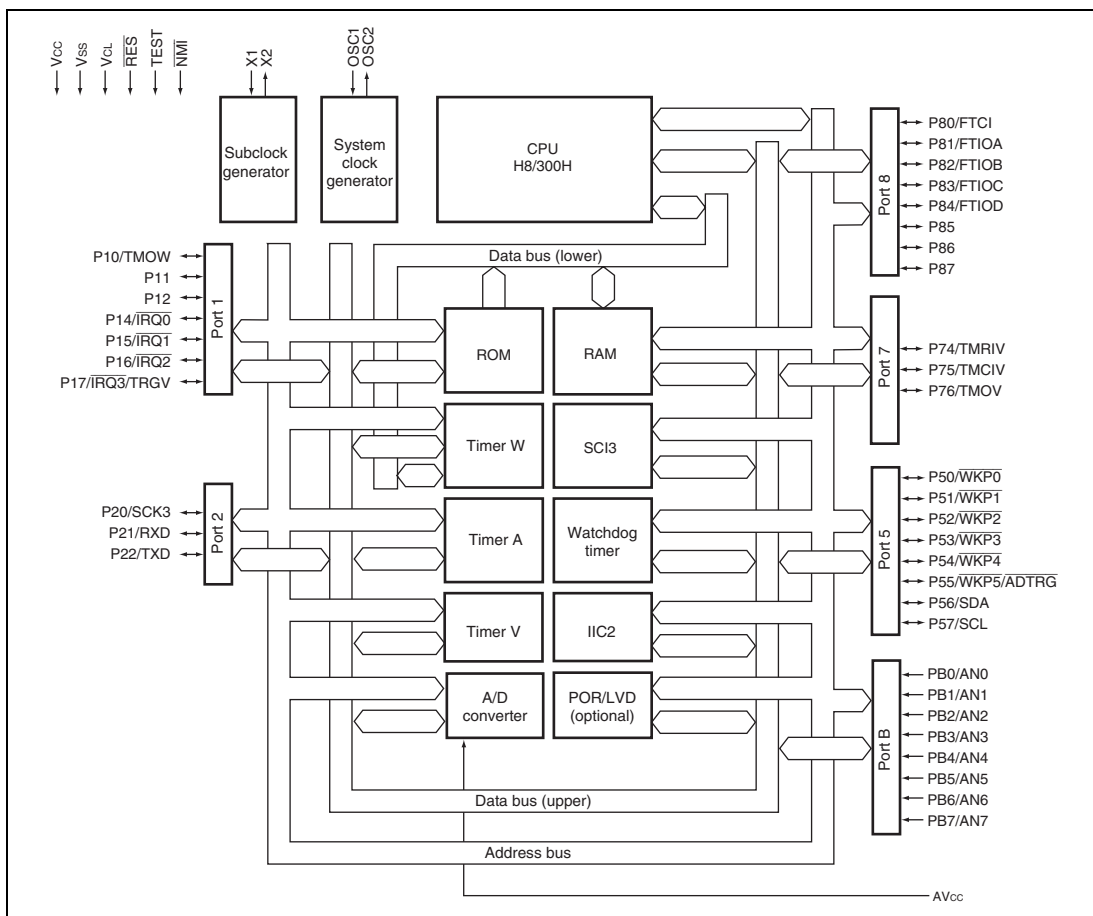


Figure 1.1 Internal Block Diagram of H8/3694 Group of F-ZTAT™ and Mask-ROM Versions

Section 3 Exception Handling

Exception handling may be caused by a reset, a trap instruction (TRAPA), or interrupts.

- Reset

A reset has the highest exception priority. Exception handling starts as soon as the reset is cleared by the $\overline{\text{RES}}$ pin. The chip is also reset when the watchdog timer overflows, and exception handling starts. Exception handling is the same as exception handling by the $\overline{\text{RES}}$ pin.

- Trap Instruction

Exception handling starts when a trap instruction (TRAPA) is executed. The TRAPA instruction generates a vector address corresponding to a vector number from 0 to 3, as specified in the instruction code. Exception handling can be executed at all times in the program execution state, regardless of the setting of the I bit in CCR.

- Interrupts

External interrupts other than NMI and internal interrupts other than address break are masked by the I bit in CCR, and kept masked while the I bit is set to 1. Exception handling starts when the current instruction or exception handling ends, if an interrupt request has been issued.

3.1 Exception Sources and Vector Address

Table 3.1 shows the vector addresses and priority of each exception handling. When more than one interrupt is requested, handling is performed from the interrupt with the highest priority.

Table 3.1 Exception Sources and Vector Address

Relative Module	Exception Sources	Vector Number	Vector Address	Priority
$\overline{\text{RES}}$ pin Watchdog timer	Reset	0	H'0000 to H'0001	High ↑ ↓ Low
—	Reserved for system use	1 to 6	H'0002 to H'000D	
External interrupt pin	NMI	7	H'000E to H'000F	
CPU	Trap instruction (#0)	8	H'0010 to H'0011	
	(#1)	9	H'0012 to H'0013	
	(#2)	10	H'0014 to H'0015	
	(#3)	11	H'0016 to H'0017	
Address break	Break conditions satisfied	12	H'0018 to H'0019	Low

entered by re-setting the P or E bit. However, PV and EV bit setting is enabled, and a transition can be made to verify mode. Error protection can be cleared only by a reset.

7.6 Programmer Mode

In programmer mode, a PROM programmer can be used to perform programming/erasing via a socket adapter, just as a discrete flash memory. Use a PROM programmer that supports the MCU device type with the on-chip 64-kbyte flash memory (FZTAT64V5).

7.7 Power-Down States for Flash Memory

In user mode, the flash memory will operate in either of the following states:

- Normal operating mode
The flash memory can be read and written to at high speed.
- Power-down operating mode
The power supply circuit of flash memory can be partly halted. As a result, flash memory can be read with low power consumption.
- Standby mode
All flash memory circuits are halted.

Table 7.7 shows the correspondence between the operating modes of this LSI and the flash memory. In subactive mode, the flash memory can be set to operate in power-down mode with the PDWND bit in FLPWCR. When the flash memory returns to its normal operating state from power-down mode or standby mode, a period to stabilize operation of the power supply circuits that were stopped is needed. When the flash memory returns to its normal operating state, bits STS2 to STS0 in SYSCR1 must be set to provide a wait time of at least 20 μ s, even when the external clock is being used.

9.3 Port 5

Port 5 is a general I/O port also functioning as an I²C bus interface I/O pin, an A/D trigger input pin, wakeup interrupt input pin. Each pin of the port 5 is shown in figure 9.3. The register setting of the I²C bus interface register has priority for functions of the pins P57/SCL and P56/SDA. Since the output buffer for pins P56 and P57 has the NMOS push-pull structure, it differs from an output buffer with the CMOS structure in the high-level output characteristics (see section 21, Electrical Characteristics).

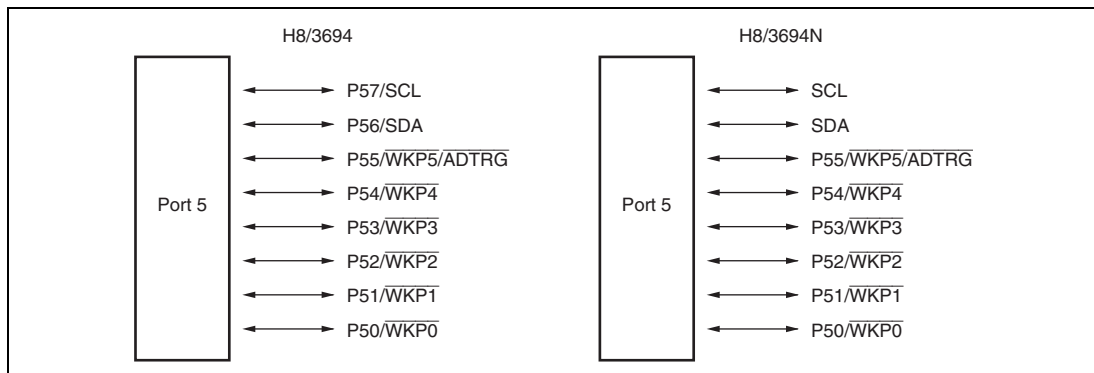


Figure 9.3 Port 5 Pin Configuration

Port 5 has the following registers.

- Port mode register 5 (PMR5)
- Port control register 5 (PCR5)
- Port data register 5 (PDR5)
- Port pull-up control register 5 (PUCR5)

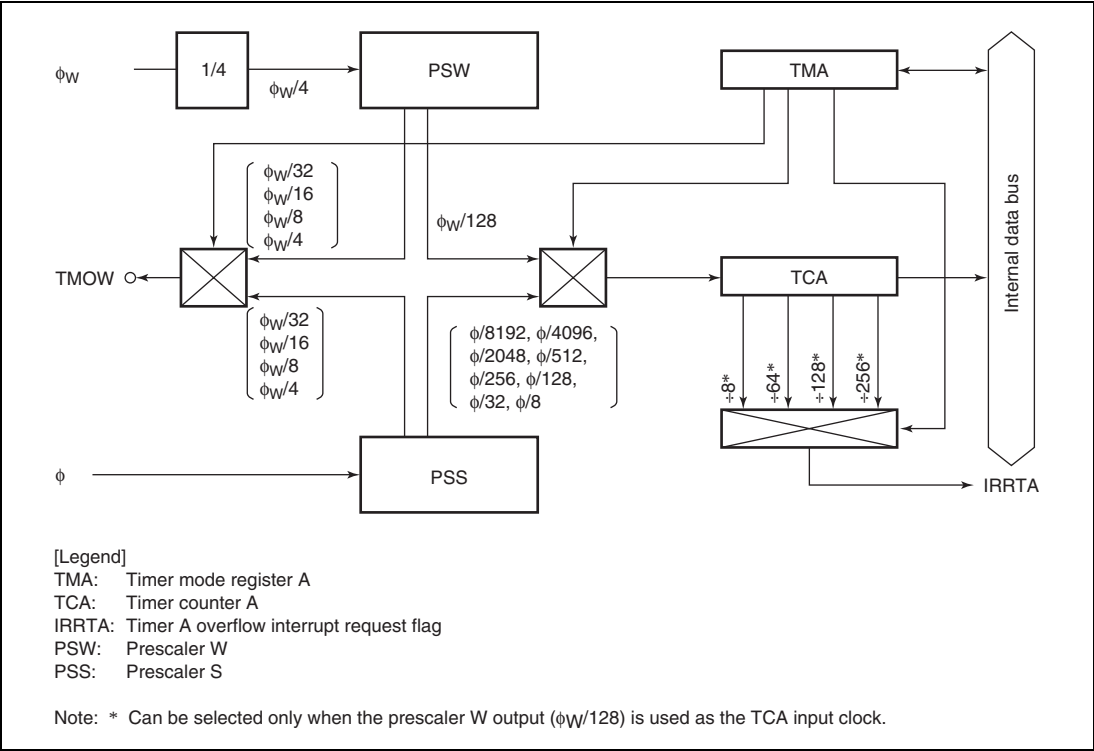


Figure 10.1 Block Diagram of Timer A

10.2 Input/Output Pins

Table 10.1 shows the timer A input/output pin.

Table 10.1 Pin Configuration

Name	Abbreviation	I/O	Function
Clock output	TMOW	Output	Output of waveform generated by timer A output circuit

Bit	Bit Name	Initial Value	R/W	Description
1	IMFB	0	R/W	Input Capture/Compare Match Flag B [Setting conditions] • TCNT = GRB when GRB functions as an output compare register • The TCNT value is transferred to GRB by an input capture signal when GRB functions as an input capture register [Clearing condition] Read IMFB when IMFB = 1, then write 0 in IMFB
0	IMFA	0	R/W	Input Capture/Compare Match Flag A [Setting conditions] • TCNT = GRA when GRA functions as an output compare register • The TCNT value is transferred to GRA by an input capture signal when GRA functions as an input capture register [Clearing condition] Read IMFA when IMFA = 1, then write 0 in IMFA

12.3.5 Timer I/O Control Register 0 (TIOR0)

TIOR0 selects the functions of GRA and GRB, and specifies the functions of the FTIOA and FTIOB pins.

Bit	Bit Name	Initial Value	R/W	Description
7	—	1	—	Reserved This bit is always read as 1.
6	IOB2	0	R/W	I/O Control B2 Selects the GRB function. 0: GRB functions as an output compare register 1: GRB functions as an input capture register

Bit	Bit Name	Initial Value	R/W	Description
5	IOB1	0	R/W	I/O Control B1 and B0
4	IOB0	0	R/W	When IOB2 = 0, 00: No output at compare match 01: 0 output to the FTIOB pin at GRB compare match 10: 1 output to the FTIOB pin at GRB compare match 11: Output toggles to the FTIOB pin at GRB compare match When IOB2 = 1, 00: Input capture at rising edge at the FTIOB pin 01: Input capture at falling edge at the FTIOB pin 1X: Input capture at rising and falling edges of the FTIOB pin
3	—	1	—	Reserved This bit is always read as 1.
2	IOA2	0	R/W	I/O Control A2 Selects the GRA function. 0: GRA functions as an output compare register 1: GRA functions as an input capture register
1	IOA1	0	R/W	I/O Control A1 and A0
0	IOA0	0	R/W	When IOA2 = 0, 00: No output at compare match 01: 0 output to the FTIOA pin at GRA compare match 10: 1 output to the FTIOA pin at GRA compare match 11: Output toggles to the FTIOA pin at GRA compare match When IOA2 = 1, 00: Input capture at rising edge of the FTIOA pin 01: Input capture at falling edge of the FTIOA pin 1X: Input capture at rising and falling edges of the FTIOA pin

Legend: X: Don't care.

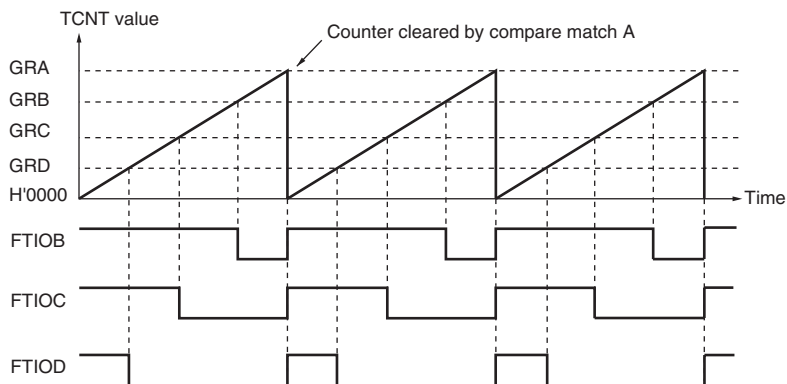


Figure 12.9 PWM Mode Example (1)

Figure 12.10 shows another example of operation in PWM mode. The output signals go to 0 and TCNT is cleared at compare match A, and the output signals go to 1 at compare match B, C, and D (TOB, TOC, and TOD = 0: initial output values are set to 1).

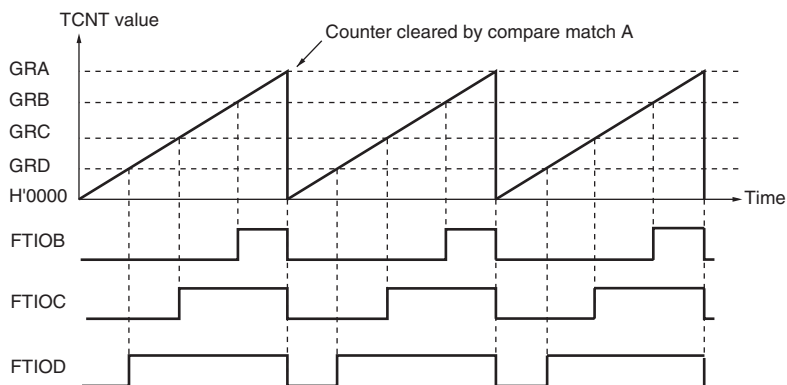


Figure 12.10 PWM Mode Example (2)

20.3 Registers States in Each Operating Mode

Register Name	Reset	Active	Sleep	Subactive	Subsleep	Standby	Module
LVDCR	Initialized	—	—	—	—	—	LVDC
LVDSR	Initialized	—	—	—	—	—	(optional)* ¹
ICCR1	Initialized	—	—	—	—	—	IIC2
ICCR2	Initialized	—	—	—	—	—	
ICMR	Initialized	—	—	—	—	—	
ICIER	Initialized	—	—	—	—	—	
ICSR	Initialized	—	—	—	—	—	
SAR	Initialized	—	—	—	—	—	
ICDRT	Initialized	—	—	—	—	—	
ICDRR	Initialized	—	—	—	—	—	Timer W
TMRW	Initialized	—	—	—	—	—	
TCRW	Initialized	—	—	—	—	—	
TIERW	Initialized	—	—	—	—	—	
TSRW	Initialized	—	—	—	—	—	
TIOR0	Initialized	—	—	—	—	—	
TIOR1	Initialized	—	—	—	—	—	
TCNT	Initialized	—	—	—	—	—	
GRA	Initialized	—	—	—	—	—	
GRB	Initialized	—	—	—	—	—	
GRC	Initialized	—	—	—	—	—	
GRD	Initialized	—	—	—	—	—	
FLMCR1	Initialized	—	—	Initialized	Initialized	Initialized	ROM
FLMCR2	Initialized	—	—	—	—	—	
FLPWCR	Initialized	—	—	—	—	—	
EBR1	Initialized	—	—	Initialized	Initialized	Initialized	
FENR	Initialized	—	—	—	—	—	Timer V
TCRV0	Initialized	—	—	Initialized	Initialized	Initialized	
TCSRv	Initialized	—	—	Initialized	Initialized	Initialized	
TCORA	Initialized	—	—	Initialized	Initialized	Initialized	
TCORB	Initialized	—	—	Initialized	Initialized	Initialized	

Item	Symbol	Applicable Pins	Test Condition	Values			Unit	Reference Figure
				Min	Typ	Max		
Input pin high width	t_{IH}	NMI, $\overline{IRQ0}$ to $\overline{IRQ3}$, $\overline{WKP0}$ to $\overline{WKP5}$, TMCIV, TMRIV, TRGV, $\overline{ADTRG}$, FTCI, FTIOA to FTIOD		2	—	—	t_{cyc} t_{subcyc}	Figure 21.3
Input pin low width	t_{IL}	NMI, $\overline{IRQ0}$ to $\overline{IRQ3}$, $\overline{WKP0}$ to $\overline{WKP5}$, TMCIV, TMRIV, TRGV, $\overline{ADTRG}$, FTCI, FTIOA to FTIOD		2	—	—	t_{cyc} t_{subcyc}	

- Notes: 1. When an external clock is input, the minimum system clock oscillation frequency is 1.0 MHz.
2. Determined by MA2, MA1, MA0, SA1, and SA0 of system control register 2 (SYSCR2).

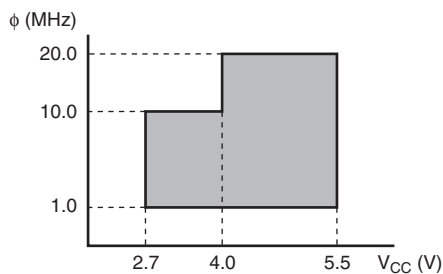
21.2.6 Flash Memory Characteristics

Table 21.8 Flash Memory Characteristics

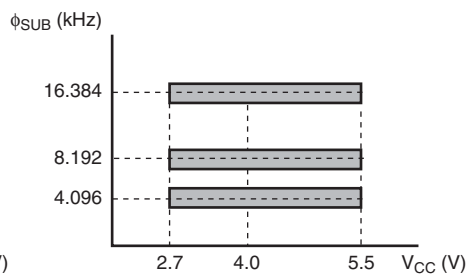
$V_{CC} = 3.0$ to 5.5 V, $V_{SS} = 0.0$ V, $T_a = -20$ to $+75^\circ\text{C}$, unless otherwise indicated.

Item		Symbol	Test Condition	Values			Unit
				Min	Typ	Max	
Programming time (per 128 bytes) * ¹ * ² * ⁴		t _p		—	7	200	ms
Erase time (per block) * ¹ * ³ * ⁶		t _E		—	100	1200	ms
Reprogramming count		N _{WEC}		1000	10000	—	Times
Programming	Wait time after SWE bit setting* ¹	x		1	—	—	μs
	Wait time after PSU bit setting* ¹	y		50	—	—	μs
	Wait time after P bit setting * ¹ * ⁴	z1	1 ≤ n ≤ 6	28	30	32	μs
		z2	7 ≤ n ≤ 1000	198	200	202	μs
		z3	Additional-programming	8	10	12	μs
	Wait time after P bit clear* ¹	α		5	—	—	μs
	Wait time after PSU bit clear* ¹	β		5	—	—	μs
	Wait time after PV bit setting* ¹	γ		4	—	—	μs
	Wait time after dummy write* ¹	ε		2	—	—	μs
	Wait time after PV bit clear* ¹	η		2	—	—	μs
	Wait time after SWE bit clear* ¹	θ		100	—	—	μs
	Maximum programming count * ¹ * ⁴ * ⁵	N		—	—	1000	Times

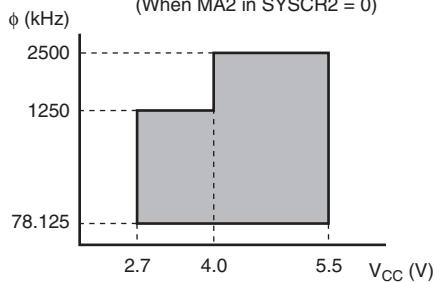
Power Supply Voltage and Operating Frequency Range



- $AV_{CC} = 3.0$ to 5.5 V
- Active mode
- Sleep mode
(When MA2 in SYSCR2 = 0)



- $AV_{CC} = 3.0$ to 5.5 V
- Subactive mode
- Subsleep mode



- $AV_{CC} = 3.0$ to 5.5 V
- Active mode
- Sleep mode
(When MA2 in SYSCR2 = 1)

Table A.1 Instruction Set**1. Data Transfer Instructions**

Mnemonic	Operand Size	Addressing Mode and Instruction Length (bytes)								Operation	Condition Code						No. of States ^{*1}	
		#xx	Rn	@ERn	@(d, ERn)	@-ERn/@ERn+	@aa	@(d, PC)	@@aa		I	H	N	Z	V	C	Normal	Advanced
MOV	MOV.B #xx:8, Rd	B	2							#xx:8 → Rd8	—	—	↕	↕	0	—		2
	MOV.B Rs, Rd	B		2						Rs8 → Rd8	—	—	↕	↕	0	—		2
	MOV.B @ERs, Rd	B			2					@ERs → Rd8	—	—	↕	↕	0	—		4
	MOV.B @(d:16, ERs), Rd	B				4				@(d:16, ERs) → Rd8	—	—	↕	↕	0	—		6
	MOV.B @(d:24, ERs), Rd	B					8			@(d:24, ERs) → Rd8	—	—	↕	↕	0	—		10
	MOV.B @ERs+, Rd	B					2			@ERs → Rd8 ERs32+1 → ERs32	—	—	↕	↕	0	—		6
	MOV.B @aa:8, Rd	B						2		@aa:8 → Rd8	—	—	↕	↕	0	—		4
	MOV.B @aa:16, Rd	B						4		@aa:16 → Rd8	—	—	↕	↕	0	—		6
	MOV.B @aa:24, Rd	B						6		@aa:24 → Rd8	—	—	↕	↕	0	—		8
	MOV.B Rs, @ERd	B			2					Rs8 → @ERd	—	—	↕	↕	0	—		4
	MOV.B Rs, @(d:16, ERd)	B				4				Rs8 → @(d:16, ERd)	—	—	↕	↕	0	—		6
	MOV.B Rs, @(d:24, ERd)	B					8			Rs8 → @(d:24, ERd)	—	—	↕	↕	0	—		10
	MOV.B Rs, @-ERd	B					2			ERd32-1 → ERd32 Rs8 → @ERd	—	—	↕	↕	0	—		6
	MOV.B Rs, @aa:8	B						2		Rs8 → @aa:8	—	—	↕	↕	0	—		4
	MOV.B Rs, @aa:16	B						4		Rs8 → @aa:16	—	—	↕	↕	0	—		6
	MOV.B Rs, @aa:24	B						6		Rs8 → @aa:24	—	—	↕	↕	0	—		8
	MOV.W #xx:16, Rd	W	4							#xx:16 → Rd16	—	—	↕	↕	0	—		4
	MOV.W Rs, Rd	W		2						Rs16 → Rd16	—	—	↕	↕	0	—		2
	MOV.W @ERs, Rd	W			2					@ERs → Rd16	—	—	↕	↕	0	—		4
	MOV.W @(d:16, ERs), Rd	W				4				@(d:16, ERs) → Rd16	—	—	↕	↕	0	—		6
	MOV.W @(d:24, ERs), Rd	W					8			@(d:24, ERs) → Rd16	—	—	↕	↕	0	—		10
	MOV.W @ERs+, Rd	W					2			@ERs → Rd16 ERs32+2 → @ERd32	—	—	↕	↕	0	—		6
	MOV.W @aa:16, Rd	W						4		@aa:16 → Rd16	—	—	↕	↕	0	—		6
	MOV.W @aa:24, Rd	W						6		@aa:24 → Rd16	—	—	↕	↕	0	—		8
	MOV.W Rs, @ERd	W			2					Rs16 → @ERd	—	—	↕	↕	0	—		4
	MOV.W Rs, @(d:16, ERd)	W				4				Rs16 → @(d:16, ERd)	—	—	↕	↕	0	—		6
	MOV.W Rs, @(d:24, ERd)	W					8			Rs16 → @(d:24, ERd)	—	—	↕	↕	0	—		10

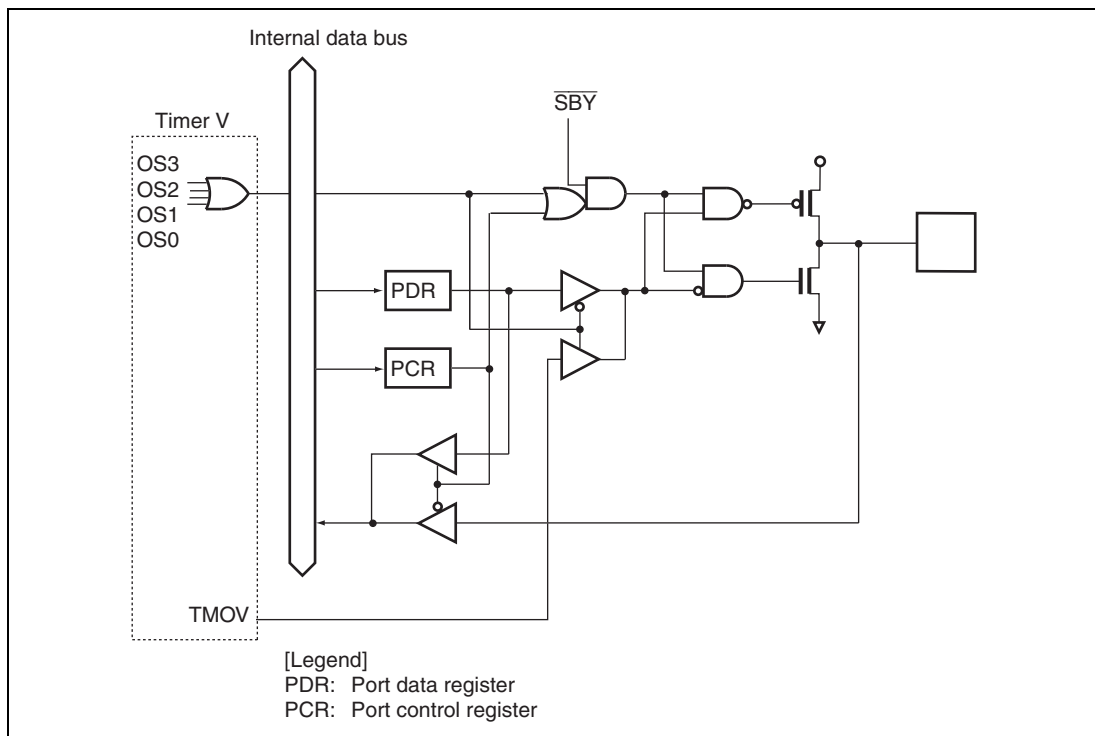


Figure B.11 Port 7 Block Diagram (P76)

Item	Page	Revision (See Manual for Details)
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Figure 5.3 Typical Connection to Crystal Resonator

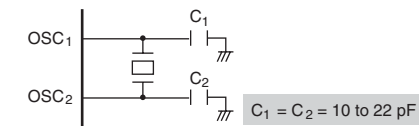
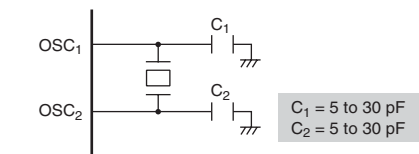


Figure 5.5 Typical Connection to Ceramic Resonator	71	
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Section 6 Power-Down Modes	76	
6.1.1 System Control Register 1 (SYSCR1)		

Bit	Bit Name	Description
3	NESEL	Noise Elimination Sampling Frequency Select
The subclock pulse generator generates the watch clock signal (ϕ_w) and the system clock pulse generator generates the oscillator clock (ϕ_{osc}). This bit selects the sampling frequency of the oscillator clock when the watch clock signal (ϕ_w) is sampled. When $\phi_{osc} = 4 \text{ to } 20 \text{ MHz}$, clear NESEL to 0.		

Section 8 RAM	107	
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Note: * When the **E7** or **E8** is used, area H'F780 to H'FB7F must not be accessed.

Section 13 Watchdog Timer	184	
13.2.1 Timer Control/Status Register WD (TCSRWD)		

Bit	Bit Name	Description
4	TCSRWE	Timer Control/Status Register WD Write Enable

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